	Ty pe		Hi ts	Search Text	DBs	Time Stam p	Comme nts	Error Defini tion	Erro rs
1	BR S	L 1	0	(substrate with dummy) and (one near2 by near2 one)	USPAT; EPO; JPO	2004/ 08/23 09:31			0
2	BR S	L 2	0	(wafer with dummy) and (one near2 by near2 one)	USPAT; EPO; JPO	2004/ 08/23 09:31			0
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4	BR S	L 4	52	("4836905" "4923584" "4643629" "5186718" "3652444" "3981791" "4226897" "4311427" "4313815" "4449885" "4457661" "4534314" "4563240" "4634331" "4705951" "4715764" "4851101" "4836733" "4836905" "4895107" "4902934" "4903937" "4909695" "4911597" "4915564" "4917556" "5007981" "5292393" "5452166" "5504033" "5504347" "5556714" "5651858" "5675461" "4313783" "4318767" "4969790" "4924890" "4936329" "5014217" "5007981" "4138306" "4576698" "5014217" "5351415" "4643629" "4824309" "4951601" "5509771" "5462397" "5685684" "4923584" "5436848").pn.	USPAT; EPO; JPO	2004/ 08/23 10:19			0
5	BR S	L 5	1	4 and dummy	USPAT; EPO; JPO	2004/ 08/23 09:37			0

	Ty pe		Hi ts	Search Text	DBs	Time Stam p	Amana	Error Defini tion	Erro rs
6	BR S	L 6	50 51	((substrate wafer) with dummy)	USPAT; EPO; JPO	2004/ 08/23 09:37			0
7	BR S		10 10	6 and vacuum	USPAT; EPO; JPO	2004/ 08/23 09:37			0
8	BR S		21 9	7 and cassette	USPAT; EPO; JPO	2004/ 08/23 09:38			0
9	BR S	L 9	59	8 and (34/\$.ccls. 134/\$.ccls.)	USPAT; EPO; JPO	2004/ 08/23 09:42			0
10	BR S	L 10	1	8 not kato	USPAT; EPO; JPO	2004/ 08/23 09:55	·		0
11	BR S	L 11	1	5169407.pn.	USPAT; EPO; JPO	2004/ 08/23 09:57			0
12	BR S	L 12	28 2	dummy with cassette	USPAT; EPO; JPO	2004/ 08/23 09:58			0
13	BR S	L 13	10 2	12 and vacuum	USPAT; EPO; JPO	2004/ 08/23 09:58			0
14	BR S	L 14	62	13 and (cassette with table)	USPAT; EPO; JPO	2004/ 08/23 10:06			0
	BR S	L 15	:	6 and @py<1991	USPAT; EPO; JPO	2004/ 08/23 10:07	·		0
16	BR S	L 16	19	15 and (dummy with cassette)	USPAT; EPO; JPO	2004/ 08/23 10:18			0
	BR S	L 17	1	4923584.pn.	USPAT; EPO; JPO	2004/ 08/23 10:19			0
IIX I	BR S	L 18	33	4 and @py<1991	USPAT; EPO; JPO	2004/ 08/23 10:19			0

	Document ID	Issue Date	l itle	Current OR	Current XRef	Inventor
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2	US 4943767 A		Automatic wafer position aligning method for wafer prober	324/758	348/87	Yokota, Keiichi
3	US 4848270 A	L .	Method and apparatus for forming thin organic film	118/402		Wakayama, Shigeru et al.
4	US 4776744 A	1988 1011	Systems and methods for wafer handling in semiconductor process equipment	414/217	269/254R; ; 269/287; 414/416.0 9; 414/806; 414/937; 414/938;	Stonestreet, Paul et al.
5	US 4759681 A	t :	End station for an ion implantation apparatus	414/416. 03		Nogami, Mamoru
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7	JP 02297925 A	1990	METHOD AND APPARATUS FOR TRANSFER OF WAFER IN VERTICAL CVD DIFFUSING DEVICE AND CONTROLLER			HARADA, YASUHIR O et al.
8	JР 02292825 A		CLEANING PROCESS FOR WAFER PROCESSING SOLUTION		204/164	SHIRAISHI , MASATOS HI
9	JP 02106923 A		HEAT TREATING METHOD FOR SUBSTRATE		29/25.01	TAKANAB E, EIICHIRO et al.

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11	JР 62132321 A	1987 0615				KANEKO, KAZUAKI et al.
12	JP 62073631 A		INTO NITE AT THE INTE		29/25.01	KOSAKA, HIROSHI et al.
13	JP 62023116 A	1987 0131	WET SEMICONDUCTOR MANUFACTURING EQUIPMENT		34/58	ЕЛПІ, IWAO
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16	JP 61141122 A	1986 0628	EQUIPMENT FOR MANUFACTURING SEMICONDUCTOR DEVICE		118/724; 257/E21. 135	KATO, HIDEAKI
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